

SWS1110

High Performance Open and Closed Loop Interface IC for Capacitive MEMS Gyroscope and Accelerometer

General Description

The SWS1110 is an open and closed loop interface IC for capacitive MEMS gyroscopes and accelerometers. The SWS1110's high performance, configurable interface supports a wide range of MEMS gyroscopes and accelerometers of various resonance frequencies and sensitivities that require a high resolution capacitive readout interface. The SWS1110 is designed to support both closed loop and open loop operation. The SWS1110 interfaces differential capacitors and is capable of sensing capacitance changes down to $50 \text{ zF}/\sqrt{\text{Hz}}$.

The SWS1110 capacitive front-end has a trimmable gain and offset to accommodate MEMS process variation during fabrication. The SWS1110 requires only a single 5V supply and few passive components to achieve a working sensor.

Features

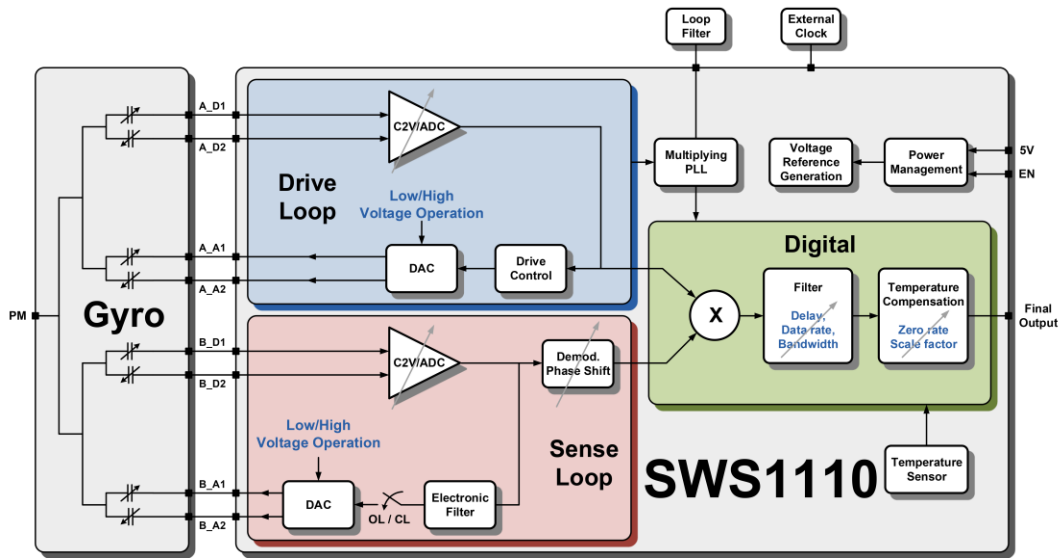
- Ultra low noise capacitive detection front-end with resolution $< 50 \text{ zF}/\sqrt{\text{Hz}}$
- Proprietary technology to minimize harmful electrical coupling
- High resolution ADC offering more than 100dB dynamic range in 100HZ BW
- Charge pump for high voltage actuation option
- Gyro drive actuation loop with programmable Automatic Amplitude Control (AAC) and tunable frequency range
- Gyroscope Coriolis output demodulation utilizing proprietary accurate phase tuning technique
- Second order scale factor and bias correction using on chip temperature sensor
- Tunable bandwidth output filter
- On chip clock generation
- Low noise reference voltage
- OTP/MTP for sensor trimming and re-calibration
- Single 5V supply operation with 23mA supply current
- 10Mb/s standard SPI interface in slave mode

Applications

The SWS1110 is targeted at applications with low resolution requirements. Typical applications include:

- Industrial
- Navigation
- Inclometers
- Motion and position measurements
- Oil exploration
- Seismic

Block Diagram



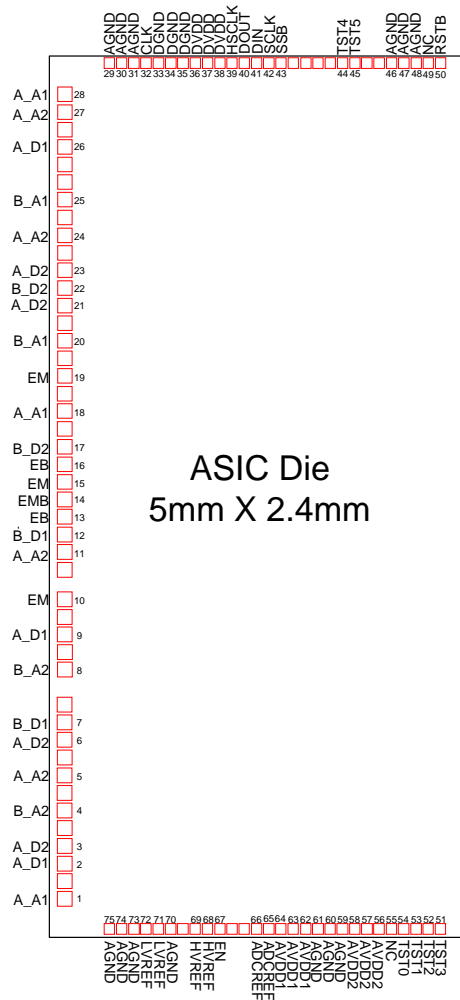
Specifications

| Parameter | Conditions | Min | Typ | Max | Units |
|--------------------------------|---|------|-----|------|------------------------|
| Front-End | | | | | |
| Supported Nominal Capacitance | | 0.25 | | 15 | pF |
| Differential Capacitance Range | Low voltage operation | | | 1.5 | pF |
| | High voltage operation | | | 0.85 | pF |
| Input Noise | At max gain setting, parasitic capacitance = 50pF | | 50 | | zF/ $\sqrt{\text{Hz}}$ |
| Linearity | At maximum voltage output | 11 | | | Bit |
| ADC Dynamic Range | In 100 BW | | 100 | | dB |
| Drive Actuation Voltage | | 4.4 | | 8 | V |
| Supported Drive Frequency | | 1.9 | | 30 | KHz |
| Output | | | | | |
| Bandwidth | | 4 | | 420 | Hz |
| Group Delay | | 2 | | 710 | Ms |
| Output Resolution | Two's complement format | | 24 | | Bit |
| Supply Voltage | | 4.75 | 5 | 5.25 | V |
| Supply Current | Low-voltage operation | | 23 | | mA |
| | High-voltage operation | | 29 | | mA |
| Power Down Current | | | 1 | | μA |
| Operating Temperature Range | | -40 | | 85 | $^{\circ}\text{C}$ |

Package Description and Pin Assignment

Bare Die & Pad-Out

Die dimensions: 5 mm by 2.4 mm and 11 mils thickness, pad opening is 60 μm by 60 μm with pitch of 70 μm , MEMS interfacing pads opening is 80 μm by 80 μm with a pitch of 100 μm (wedge bonding compatible).



Pad Distribution on Die

Pad Definition

| Pin No. | Name | X (μm) | Y (μm) | Description |
|---------|------|---------------------|---------------------|-------------------------|
| 1 | A_A1 | 92.36 | 214 | Channel A +ve Actuation |
| 2 | A_D1 | 92.36 | 414 | Channel A +ve Detection |
| 3 | A_D2 | 92.36 | 514 | Channel A -ve Detection |

| Pin No. | Name | X (µm) | Y (µm) | Description |
|---------|------|---------|---------|---------------------------|
| 4 | B_A2 | 92.36 | 714 | Channel B -ve Actuation |
| 5 | A_A2 | 92.36 | 914 | Channel A -ve Actuation |
| 6 | A_D2 | 92.36 | 1114 | Channel A -ve Detection |
| 7 | B_D1 | 92.36 | 1214 | |
| 8 | B_A2 | 92.36 | 1514 | Channel B -ve Actuation |
| 9 | A_D1 | 92.36 | 1714 | Channel A +ve Detection |
| 10 | EM | 92.36 | 1914 | Proof Mass |
| 11 | A_A2 | 92.36 | 2181 | Channel A -ve Actuation |
| 12 | B_D1 | 92.36 | 2281 | Channel B +ve Detection |
| 13 | EB | 92.36 | 2381 | MEMS substrate |
| 14 | EMB | 92.36 | 2481 | Inverted Proof Mass |
| 15 | EM | 92.36 | 2581 | Proof Mass |
| 16 | EB | 92.36 | 2681 | MEMS substrate |
| 17 | B_D2 | 92.36 | 2781 | Channel B -ve Detection |
| 18 | A_A1 | 92.36 | 2981 | Channel A +ve Actuation |
| 19 | EM | 92.36 | 3181 | Proof Mass |
| 20 | B_A1 | 92.36 | 3381 | Channel B +ve Actuation |
| 21 | A_D2 | 92.36 | 3581 | Channel A -ve Detection |
| 22 | B_D2 | 92.36 | 3681 | Channel B -ve Detection |
| 23 | A_D2 | 92.36 | 3781 | Channel A -ve Detection |
| 24 | A_A2 | 92.36 | 3981 | Channel A -ve Actuation |
| 25 | B_A1 | 92.36 | 4181 | Channel B +ve Actuation |
| 26 | A_D1 | 92.36 | 4481 | Channel A +ve Detection |
| 27 | A_A2 | 92.36 | 4681 | Channel A -ve Actuation |
| 28 | A_A1 | 92.36 | 4781 | Channel A +ve Actuation |
| 29 | AGND | 346.34 | 4957.72 | Analog Ground |
| 30 | AGND | 416.36 | 4957.72 | |
| 31 | AGND | 486.34 | 4957.72 | |
| 32 | CLK | 556.34 | 4957.72 | 5V CMOS Clock I/O |
| 33 | DGND | 626.34 | 4957.72 | Digital Ground |
| 34 | DGND | 696.34 | 4957.72 | |
| 35 | DGND | 766.34 | 4957.72 | |
| 36 | DVDD | 836.34 | 4957.72 | Chip Digital Supply (5V) |
| 37 | DVDD | 906.34 | 4957.72 | |
| 38 | DVDD | 976.34 | 4957.72 | |
| 39 | HCLK | 1046.34 | 4957.72 | External High Speed Clock |
| 40 | DOUT | 1116.34 | 4957.72 | SPI MISO |
| 41 | DIN | 1186.34 | 4957.72 | SPI MOSI |
| 42 | SCLK | 1256.34 | 4957.72 | SPI Clock |
| 43 | SSB | 1326.34 | 4957.72 | SPI Slave Select |
| 44 | TST4 | 1676.34 | 4957.72 | Test Signal 4 |
| 45 | TST5 | 1746.34 | 4957.72 | Test Signal 5 |
| 46 | AGND | 1956.34 | 4957.72 | Analog Ground |
| 47 | AGND | 2026.34 | 4957.72 | |

| Pin No. | Name | X (µm) | Y (µm) | Description |
|---------|--------|---------|---------|--|
| 48 | AGND | 2096.34 | 4957.72 | |
| 49 | NC | 2166.34 | 4957.72 | No Connection |
| 50 | RSTB | 2236.34 | 4957.72 | Chip reset 5V Active Low with Internal Pull Up |
| 51 | TST3 | 2236.34 | 42.28 | Test Signal 3 |
| 52 | TST2 | 2166.34 | 42.28 | Test Signal 2 |
| 53 | TST1 | 2096.34 | 42.28 | Test Signal 1 |
| 54 | TST0 | 2026.34 | 42.28 | Test Signal 0 |
| 55 | NC | 1956.34 | 42.28 | No Connection |
| 56 | AVDD2 | 1886.34 | 42.28 | Chip 2 nd Analog Supply (5V) |
| 57 | AVDD2 | 1816.34 | 42.28 | |
| 58 | AVDD2 | 1746.34 | 42.28 | |
| 59 | AGND | 1676.34 | 42.28 | Analog Ground |
| 60 | AGND | 1606.34 | 42.28 | |
| 61 | AGND | 1536.34 | 42.28 | |
| 62 | AVDD1 | 1466.34 | 42.28 | Chip 1 st Analog Supply (5V) |
| 63 | AVDD1 | 1396.34 | 42.28 | |
| 64 | AVDD1 | 1326.34 | 42.28 | |
| 65 | ADCREF | 1256.34 | 42.28 | ADC Reference Voltage |
| 66 | ADCREF | 1186.34 | 42.28 | |
| 67 | EN | 976.34 | 42.28 | Chip Enable Active High |
| 68 | HVREF | 906.34 | 42.28 | High Voltage Internal Reference (8V) |
| 69 | HVREF | 836.34 | 42.28 | |
| 70 | AGND | 696.34 | 42.28 | Analog Ground |
| 71 | LVREF | 626.34 | 42.28 | Low Voltage Internal Reference (4.4V) |
| 72 | LVREF | 556.34 | 42.28 | |
| 73 | AGND | 486.34 | 42.28 | Analog Ground |
| 74 | AGND | 416.34 | 42.28 | |
| 75 | AGND | 346.34 | 42.28 | |

QFN Package

Please contact Si-Ware for QFN packaging options.

Revision History

| Revision | Date | Description |
|----------|---------|----------------------------|
| 1.0 | 4-23-14 | Original datasheet created |

Contact Information

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